

DECLARATION

As the below-named inventors, we declare that:

Our residences, post office addresses, and citizenships are as stated below under our names.

We believe we are the original, first, and joint inventors of the invention entitled "METHODS AND APPARATUSES FOR MECHANICAL AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES ON PLANARIZING PADS," which is described and claimed in the foregoing specification and for which a patent is sought.

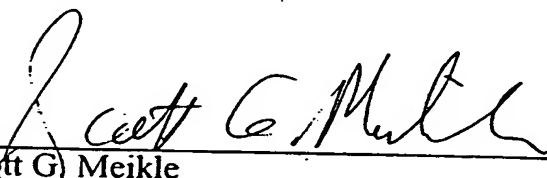
We have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to herein (if any).

We acknowledge our duty to disclose information of which we are aware which is material to patentability and examination of this application in accordance with 37 C.F.R. § 1.56(a).

We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.


Dinesh Chopra

Date 9/29/98
Residence : City of Boise, County of Ada
State of Idaho
Citizenship : India
P.O. Address : 101 E. Mallard Drive
Apt. 278
Boise, Idaho 83706


Scott G. Meikle

Date 9/29/98
Residence : City of Boise, County of Ada
State of Idaho
Citizenship : Canada
P.O. Address : 1301 East Jefferson
Boise, Idaho 83712

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Dinesh Chopra and Scott G. Meikle
Filed : Concurrently herewith
For : METHODS AND APPARATUSES FOR MECHANICAL
AND CHEMICAL-MECHANICAL PLANARIZATION OF
MICROELECTRONIC-DEVICE SUBSTRATE
ASSEMBLIES ON PLANARIZING PADS

Docket No. : 660073.698

Box Patent Application
Assistant Commissioner for Patents
Washington, DC 20231

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF ATTORNEY

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventors.

Assignee hereby appoints RICHARD W. SEED, Reg. No. 16,557; ROBERT J. BAYNHAM, Reg. No. 22,846; EDWARD W. BULCHIS, Reg. No. 26,847; GEORGE C. RONDEAU, JR., Reg. No. 28,893; DAVID H. DEITS, Reg. No. 28,066; WILLIAM O. FERRON, JR., Reg. No. 30,633; PAUL T. MEIKLEJOHN, Reg. No. 26,569; DAVID J. MAKI, Reg. No. 31,392; RICHARD G. SHARKEY, Reg. No. 32,629; DAVID V. CARLSON, Reg. No. 31,153; MAURICE J. PIRIO, Reg. No. 33,273; KARL R. HERMANN, Reg. No. 33,507; DAVID D. MCMASTERS, Reg. No. 33,963; ROBERT IANNUCCI, Reg. No. 33,514; MICHAEL J. DONOHUE, Reg. No. 35,859; CHRISTOPHER J. DALEY-WATSON,

Reg. No. 34,807; STEVEN D. LAWRENZ, Reg. No. 37,376; ROBERT G. WOOLSTON, Reg. No. 37,263; ELLEN M. BIERMAN, Reg. No. 38,079; BRYAN A. SANTARELLI, Reg. No. 37,560; CAROL NOTTENBURG, Reg. No. 39,317; PAUL T. PARKER, Reg. No. 38,264; JOHN C. STEWART, Reg. No. 40,188; DAVID W. PARKER, Reg. No. 37,414; BRIAN G. BODINE, Reg. No. 40,520; FRANK ABRAMONTE, Reg. No. 38,066; E. RUSSELL TARLETON, Reg. No. 31,800; FREDERICK M. FLIEGEL, Reg. No. 36,138; JAN C. L. MAXWELL, Reg. No. 41,181; THOMAS L. EWING, Reg. No. 34,328; CLIFTON G. GREEN, Reg. No. 41,044; KEVIN S. COSTANZA, Reg. No. 37,801; DALE C. BARR, Reg. No. 40,498; KEVIN S. ROSS, Reg. No. 42,116; PAUL F. RUSYN, Reg. No. 42,118; JOHN M. WECHKIN, Reg. No. 42,216; THOMAS E. LOOP, Reg. No. 42,810; STEPHEN J. ROSENMAN, Reg. No. 43,058; and BRIAN L. JOHNSON, Reg. No. 40,033, comprising the firm of SEED AND BERRY LLP, 6300 Columbia Center, Seattle, Washington 98104-7092; along with MICHAEL L. LYNCH, Reg. No. 30,871; LIA M. PAPPAS, Reg. No. 34,095; W. ERIC WEBOSTAD, Reg. No. 35,406; WALTER D. FIELDS, Reg. No. 37,130; CHARLES B. BRANTLEY, II, Reg. No. 38,086; SUSAN B. COLLIER, Reg. No. 34,566; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of Micron Technology, Inc., 8000 South Federal Way, Boise, Idaho 83706-9632, as its attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. Please direct all telephone calls to Paul T. Parker at (206) 622-4900 and telecopies to (206) 682-6031.

Please direct all communications to:

Paul T. Parker, Esq.
Seed and Berry LLP
6300 Columbia Tower
701 Fifth Avenue
Seattle, Washington 98104-7092

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., filed concurrently herewith for recording, a copy of which is attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC.
ASSIGNEE

Sept 30, 1998
DATE

Michael L. Lynch
Michael L. Lynch
Chief Patent Counsel

Enclosure:
Copy of Assignment

\\users\\kristineo\\ptpkko\\660073\\0322

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

**Dinesh Chopra and
Scott G. Meikle**

Docket No.: 660073.698

Disclosure Number: 97-1481

Filed: Concurrently herewith

For: METHODS AND APPARATUSES FOR MECHANICAL AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES ON PLANARIZING PADS

ASSIGNMENT:

X Enclosed for recording

— Previously recorded

Date: _____

Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

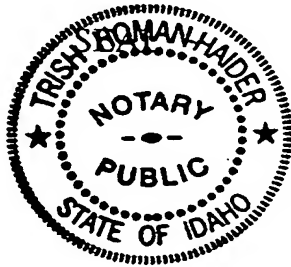
SELL, ASSIGN AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83706-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "METHODS AND APPARATUSES FOR MECHANICAL AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES ON PLANARIZING PADS"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the

Scott G. Meikle
Scott G. Meikle

Date: Sept. 29/98

STATE OF IDAHO)
) ss.
County of Ada

BEFORE ME, this 29th day of September 1998, personally appeared the above-named individual, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he executed the same of his own free will for the purpose therein expressed.



Trish Roman-Hader
Notary or Consular Officer
My Commission Expires 3-26-03

\\users\\kristineo\\ptpkko\\660073\\0320

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, DC 20231.

April 5, 2000
Date

Debra A. Daniel
Debra A. Daniel

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants :	Dinesh Chopra and Scott G. Meikle	Attorney Docket No.:	660073:698 (500077.01)
Serial No. :	09/164,915	Group Art Unit :	3725
Filed :	October 1, 1998	Examiner :	William Hong
Title :	METHODS AND APPARATUSES FOR MECHANICAL AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES ON PLANARIZING PADS		

TRANSMITTAL FOR REVOCATION AND SUBSTITUTE POWER OF ATTORNEY

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith and attached hereto as Addendum A is a true and correct copy of the Revocation and Substitute Power of Attorney executed January 3, 2000, in the above-identified application. The above-identified application is identified on Exhibit A.

Pursuant to 37 C.F.R. § 3.73, Michael L. Lynch, duly authorized designee of Assignee, has certified that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., recorded under Reel 9510 / Frame 0560, and certified that to the best of his knowledge and belief, title remains in the name of the Assignee.

Respectfully submitted,

DORSEY & WHITNEY LLP

Steven H. Arterberry
Steven H. Arterberry
Registration No. 46,314

Enclosures:

Addendum A
Exhibit A

1420 Fifth Avenue, Suite 3400
Seattle, Washington 98101-4010
(206) 903-8800 (telephone)
(206) 903-8200 (fax)

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ADDENDUM A

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Assistant Commissioner for Patents
Washington, DC 20231

REVOCATION AND SUBSTITUTE POWER OF ATTORNEY

Sir:

In the matter of the patent applications identified in Exhibit A attached hereto, I, MICHAEL L. LYNCH, declare that I am a duly authorized designee of Micron Technology, Inc., the ASSIGNEE of the entire right, title and interest in and to the above-referenced patent applications. Documentary evidence of chain of title from the original owner to ASSIGNEE has been or is concurrently being filed with and recorded by the United States Patent Office. The evidentiary documents referred to in the instant Revocation and Power of Attorney have been reviewed by the undersigned, and it is certified that, to the best of ASSIGNEE's knowledge and belief, title is held solely in and by ASSIGNEE.

On behalf ASSIGNEE, I revoke all power of attorney heretofore given, and hereby appoint EDWARD W. BULCHIS, Reg. No. 26,847; JON F. TUTTLE, Reg. No. 25,713; PAUL T. MEIKLEJOHN, Reg. No. 26,569; GLENN P. RICKARDS, Reg. No. 29,428; DALE C. BARR, Reg. No. 40,498; KIMTON N. ENG, Reg. No. 43,605; DAVID E. BOONE, Reg. No. 27,857; SCOTT W. DOYLE, Reg. No. 39,176; REED R. HEIMBECHER, Reg. No. 36,353; JOHN T. KENNEDY, Reg. No. 42,717; GREGORY D. LEIBOLD, Reg. No. 36,408; GARY M. POLUMBUS, Reg. No. 25,364; THOMAS H. YOUNG, Reg. No. 25,796; W. ROBINSON H. CLARK, Reg. No. 41,530; GREGORY J. GLOVER, Reg. No. 34,173; JOHN K. HARROP, Reg. No. 41,817; CHRIS McWHINNEY, Reg. No. 42,875; ALDO NOTO, Reg. No. 35,628; MATTHEW PHILLIPS, Reg. No. 43,403; JOHN W. RYAN, Reg. No. 33,771; AMI P. SHAH,

Reg. No. 42,143; SEAN S. WOODEN, Reg. No. 43,997; MICHAEL C. GILCHRIST, Reg. No. 40,619; BRIAN J. LAURENZO, Reg. No. 34,207; SHANE COLEMAN, Reg. No. 44,623; RONALD J. BROWN, Reg. No. 29,016; DAVID E. BRUHN, Reg. No. 36,762; DAVID N. FRONEK, Reg. No. 25,678; JOSEPH F. HAAG, Reg. No. 42,612; STUART R. HEMPHILL, Reg. No. 28,084; GRANT A. JOHNSON, Reg. No. 42,696; KENNETH E. LEVITT, Reg. No. 39,747; NIALA A. MACLEOD, Reg. No. 41,963; SCOTT A. MARKS, Reg. No. 44,902; DEVAN V. PADMANABHAN, Reg. No. 38,262; GERALD H. SULLIVAN, Reg. No. 36,311; BRIAN PARK, Reg. No. P-45,519; MARK W. ROBERTS, Reg. No. P-46,160; STEVEN H. ARTERBERRY, Reg. No. P-46,314; of the firm of DORSEY & WHITNEY LLP; along with MICHAEL L. LYNCH, Reg. No. 30,871; LIA M. PAPPAS, Reg. No. 34,095; WALTER D. FIELDS, Reg. No. 37,130; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of MICRON TECHNOLOGY, INC., 8000 South Federal Way, Boise, Idaho 83706-9632, as its attorneys to transact all business in the Patent and Trademark Office connected therewith.

Please direct all future correspondence and telephone calls to:

Edward W. Bulchis
DORSEY and WHITNEY LLP
U.S. Bank Centre, Suite 3400
1420 Fifth Avenue
Seattle, Washington 98101
(206)903-8800
(206)903-8820 facsimile.

ASSIGNEE:

Micron Technology, Inc.

Jan 3, 2000
Date


By 
Michael L. Lynch
Chief Patent Counsel

EXHIBIT A

09/164,915	660073.698	Dinesh Chopra and Scott Meikle	01-Oct-98	Methods and Apparatuses for Mechanical and Chemical-Mechanical Planarization of Microelectronic-Device Substrate Assemblies on Planarizing Pads
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